# DATA SHEET 74F545 Octal bidirectional transceiver (with 3-State inputs/outputs)

INTEGRATED CIRCUITS

Product specification

IC15 Data Handbook



1990 Mar 01





74F545

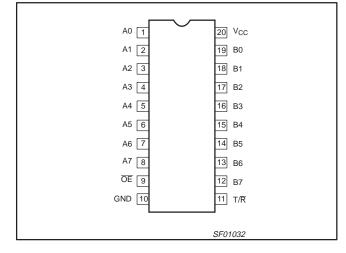
### **FEATURES**

- High impedance NPN base inputs for reduced loading (70μA in High and Low states) output
- 8-bit bidirectional data flow reduces system package count
- 3-State inputs/outputs for interfacing with bus oriented systems
- 24mA and 64mA bus drive capability on A and B ports, respectively
- Transmit/Receive and Output Enable simplify control logic

### DESCRIPTION

The 74F545 is an 8-bit, 3-State, high speed transceiver. It provides bidirectional drive for the bus-oriented microprocessor and digital communications systems. Straight through bidirectional transceivers are featured, with 24mA bus drive capability on the A ports and 64mA bus drive capability on the B ports. One input, Transmit/Receive (T/ $\mathbb{R}$ ) determines the direction of logic signals through the bidirectional transceiver. Transmit enables data from A ports to B ports; Receive enables data from B ports to A ports. The Output Enable input disables both A and B ports by placing them in a 3-State condition. The 74F545 performs the same function as the 74F245, the only difference being package pin assignment.

### **PIN CONFIGURATION**



TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F545	4.0ns	87mA

### **ORDERING INFORMATION**

DESCRIPTION	COMMERCIAL RANGE V <sub>CC</sub> = 5V ±10%, T <sub>amb</sub> = 0°C to +70°C	PKG DWG #
20-Pin Plastic DIP	N74F545N	SOT146-1
20-Pin Plastic SOL	N74F545D	SOT163-1

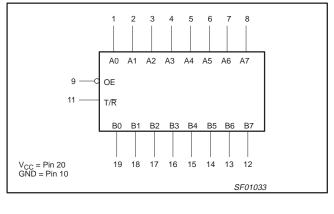
### INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

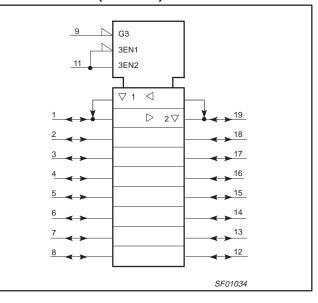
PINS	DESCRIPTION	74F(U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
A0–A7, B0–B7	Data inputs	3.5/0.117	70μΑ/70μΑ
ŌĒ	Output Enable input (active Low)	2.0/0.067	40μΑ/40μΑ
T/R	Transmit/Receive input	2.0/0.067	40μΑ/40μΑ
A0 - A7	Port A 3-State outputs	150/40	3.0mA/24mA
B0 - B7	Port B 3-State outputs	750/107	15mA/64mA

NOTE: One (1.0) FAST Unit Load is defined as: 20µA in the High state and 0.6mA in the Low state.

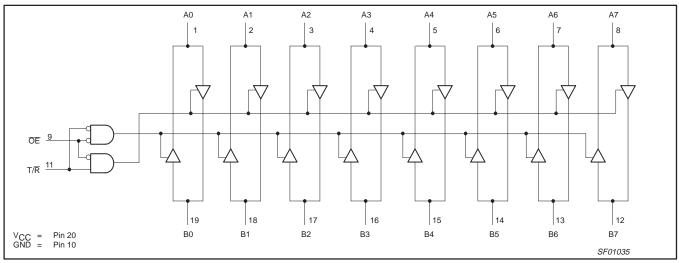
# 74F545

### LOGIC SYMBOL





## LOGIC DIAGRAM



### **FUNCTION TABLE**

INP	JTS	OUTPUTS
OE	T/R	
L	L	Bus B data to Bus A
L	Н	Bus A data to Bus B
н	Х	Z

H = High voltage level

L = Low voltage level

X = Don't care Z = High impedance "off" state

# LOGIC SYMBOL (IEEE/IEC)

# 74F545

### **ABSOLUTE MAXIMUM RATINGS**

(Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER		RATING	UNIT
V <sub>CC</sub>	Supply voltage		-0.5 to +7.0	V
V <sub>IN</sub>	Input voltage		-0.5 to +7.0	V
I <sub>IN</sub>	Input current		-30 to +5.0	mA
V <sub>OUT</sub>	Voltage applied to output in High output state	-0.5 to +5.5	V	
	Current emplied to output in Low output state	A0–A7	48	mA
lout	Current applied to output in Low output state	B0–B7	128	mA
T <sub>amb</sub>	Operating free-air temperature range		0 to +70	°C
T <sub>stg</sub>	Storage temperature		-65 to +150	°C

### **RECOMMENDED OPERATING CONDITIONS**

SYMPOL	SYMBOL PARAMETER					
STWBOL			MIN	NOM	MAX	UNIT
V <sub>CC</sub>	Supply voltage		4.5	5.0	5.5	V
V <sub>IH</sub>	High-level input voltage		2.0			V
VIL	Low-level input voltage				0.8	V
I <sub>IK</sub>	Input clamp current				-18	mA
la.	High lovel output outpost	A0-A7			-3	mA
ЮН	High-level output current	B0–B7			-15	mA
	A0–A7				24	mA
IOL	Low-level output current	B0–B7			64	mA
T <sub>amb</sub>	Operating free-air temperature range	-	0		70	°C

# 74F545

### DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMETER		TEST CONDITIONS <sup>1</sup>			LIMITS			
STNIDUL						MIN	TYP <sup>2</sup>	MAX	UNIT
		A0–A7		1 - 2mA	±10%V <sub>CC</sub>	2.4			V
	High-level output voltage	B0–B7	V <sub>CC</sub> = MIN, V <sub>IL</sub> = MAX,	$I_{OH} = -3mA$	±5%V <sub>CC</sub>	2.7	3.3		V
V <sub>OH</sub>	High-level output voltage	B0B7	$V_{IH} = MIN$	I <sub>OH</sub> = -15mA	±10%V <sub>CC</sub>	2.0			V
		00-07		10H = -10HA	±5%V <sub>CC</sub>	2.0			V
		A0-A7		$I_{OI} = 24mA$	±10%V <sub>CC</sub>		0.35	0.50	V
Va	Low-level output voltage	A0-A7	V <sub>CC</sub> = MIN, V <sub>IL</sub> = MAX,	IOL = 2411A	±5%V <sub>CC</sub>		0.35	0.50	V
V <sub>OL</sub>	Low-level output voltage	B0B7	$V_{IH} = MIN$	I <sub>OL</sub> = MAX	±10%V <sub>CC</sub>			0.55	V
		в0-в <i>1</i>		IOL = MAX	±5%V <sub>CC</sub>		0.42	0.55	V
V <sub>IK</sub>	Input clamp voltage		Vc	$C = MIN, I_I = I_{IK}$	(		-0.73	-1.2	V
Input current at		OE, T/R	$V_{CC} = 0.0V, V_{I} = 7.0V$				100	μΑ	
lı	maximum input voltage	A0–A7, B0–B7	V <sub>CC</sub>	= 5.5V, V <sub>I</sub> = 5.5	5V			1.0	mA
I <sub>IH</sub>	High-level input current	OE, T/R	V <sub>CC</sub>	= MAX, V <sub>I</sub> = 2.7	7V			40	μA
IIL	Low-level input current	only	V <sub>CC</sub>	= MAX, V <sub>I</sub> $=$ 0.8	5V			-40	μΑ
I <sub>OZH</sub> +I <sub>IH</sub>	Off-state output current High-level voltage applied		V <sub>CC</sub>	= MAX, V <sub>I</sub> = 2.7	7V			70	μΑ
I <sub>OZL</sub> +I <sub>IL</sub>	Off-state output current Low-level voltage applied		$V_{CC} = MAX, V_I = 0.5V$				-70	μΑ	
1	Short-circuit output	A0–A7				-60		-150	mA
los	current <sup>3</sup>	B0–B7		$V_{CC} = MAX$		-100		-225	μA
		I <sub>ССН</sub>		T/R=An=4.5V,	, OE=GND		84	100	mA
I <sub>CC</sub>	Supply current (total) <sup>4</sup>	I <sub>CCL</sub>	$V_{CC} = MAX$	OE=T/R =Bn=	⊧GND		96	120	mA
		I <sub>CCZ</sub>		$T/\overline{R}$ =Bn=GND, $\overline{OE}$ =4.5V			96	120	mA

### NOTES:

1. For conditions shown as MIN or MAX, use the appropriate value under the recommended operating conditions for the applicable type.

2. All typical values are at  $V_{CC} = 5V$ ,  $T_{amb} = 25^{\circ}C$ .

3. Not more than one output should be shorted at a time. For testing I<sub>OS</sub>, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I<sub>OS</sub> should be performed last.

4. Measure I<sub>CC</sub> with outputs open.

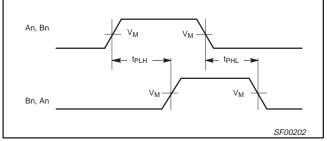
### AC ELECTRICAL CHARACTERISTICS

					LIMIT	ſS		
SYMBOL	PARAMETER	TEST CONDITIONS	v	<sub>imb</sub> = +25° <sup>′</sup> CC = +5.0′ i0pF, R <sub>L</sub> =	V	V <sub>CC</sub> = +5.	C to +70°C 0V ± 10% R <sub>L</sub> = 500Ω	UNIT
			MIN	TYP	MAX	MIN	MAX	
t <sub>PLH</sub>	Propagation delay	Waveform 1	1.5	3.5	5.5	1.5	6.5	ns
t <sub>PHL</sub>	An to Bn, Bn to An		2.5	4.5	6.5	2.5	7.0	ns
t <sub>PZH</sub>	Output Enable time	Waveform 2	6.0	8.5	10.5	6.0	11.0	ns
t <sub>PZL</sub>	to High or Low level	Waveform 3	5.5	8.0	9.5	5.5	10.0	ns
t <sub>PHZ</sub>	Output Disable time	Waveform 2	2.5	5.0	7.0	2.5	8.0	ns
t <sub>PLZ</sub>	from High or Low level	Waveform 3	2.0	4.5	6.5	2.0	7.5	ns

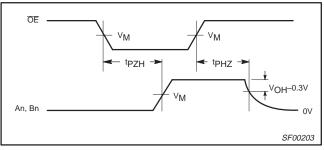
# 74F545

### AC WAVEFORMS

For all waveforms,  $V_M = 1.5V$ .

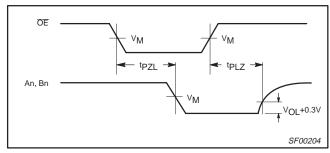


Waveform 1. Propagation Delay Data for Non-Inverting Output

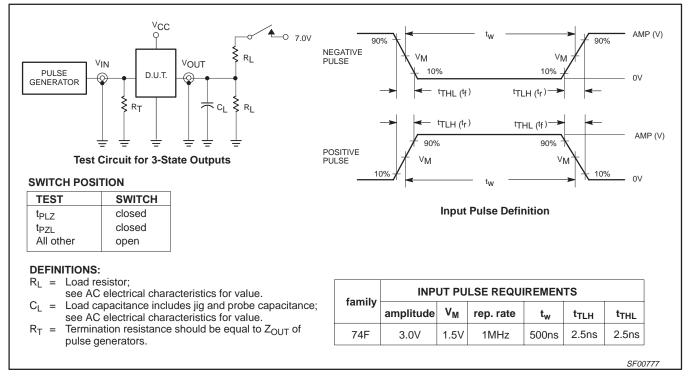


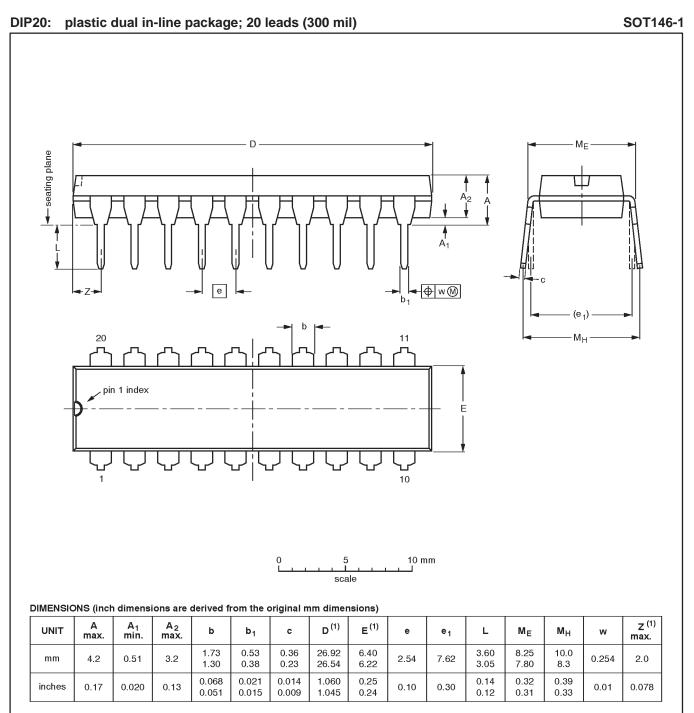
Waveform 2. 3-State Output Enable Time to High Level and Output Disable Time from High Level

### **TEST CIRCUIT AND WAVEFORM**



Waveform 3. 3-State Output Enable Time to Low Level and Output Disable Time from Low Level





### Note

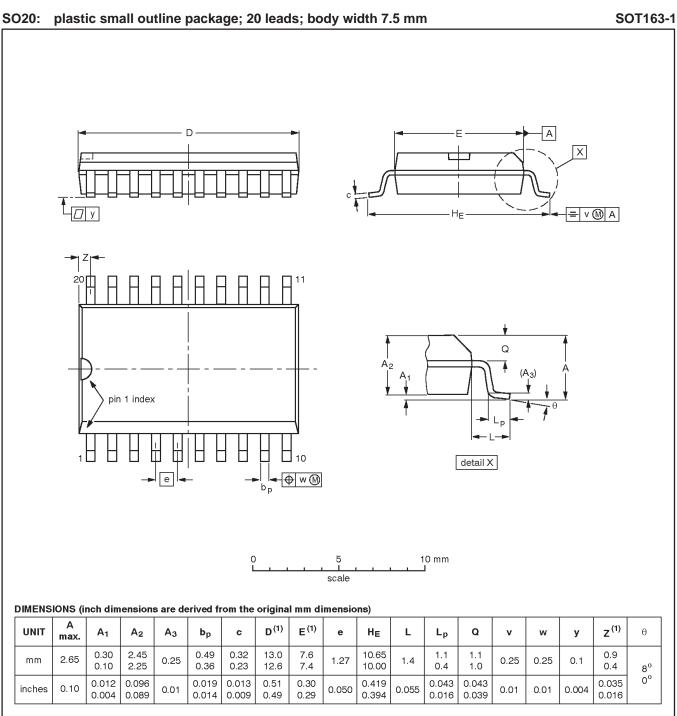
1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT146-1			SC603			<del>-92-11-17-</del> 95-05-24

74F545

74F545

# Octal bidirectional transceiver (with 3-State inputs/outputs)



### Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE	LINE REFERENCES					ISSUE DATE	
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT163-1	075E04	MS-013AC				<del>-95-01-24</del> 97-05-22	

74F545

NOTES

# 74F545

### Data sheet status

Data sheet status	Product status	Definition <sup>[1]</sup>
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
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